Product / Process Change Notification

N° 2020-003-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Harmonization of chip top metallization and bill of material for dedicated OptiMOS™ products in PG-TDSON-8 & PG-TSDSON-8 package including capacity extension for products in PG-TDSON package at Infineon Technologies Wuxi Co., Ltd., China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2 February 2021**.
- Infineon aligns with the widely-recognized JEDEC STANDARD **"JESD46",** which stipulates:
  "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification

N° 2020-003-A

▸ Products affected:

Please refer to attached affected product list 1_cip20003_a

▸ Detailed Change Information:

Subject:

- Harmonization of chip top solder pad metallization and bill of material for dedicated OptiMOS™ products in PG-TDSON-8 and PG-TSDSON-8 packages
- Capacity extension at Infineon Technologies Wuxi Co., Ltd., China (IFX Wuxi) for PG-TDSON-8 packages

Reason:

- Increase of high volume manufacturing capability
- Implementation of additional assembly site for improved delivery security

Description:	Old	New
Chip top solder pad metallization	■ Ni/Ag based	■ Cu based
Wafer Thickness	■ 175µm	■ 77µm
Gate Wire	■ 50µm Cu	■ 30µm Au
Assembly & Final Test location for PG-TDSON-8 packages	■ Infineon Technologies Malaysia Sdn. Bhd., Melaka	■ Infineon Technologies Malaysia Sdn. Bhd., Melaka ■ Infineon Technologies Wuxi Co., Ltd., China
Mould compound for PG-TDSON-8 package	■ CEL 1772	■ CEL 9240

▸ Product Identification:

Internal traceability via Baunumber, Lotnumber, date code

▸ Impact of Change:

NO change of existing datasheet parameters.

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.

NO change in package outline dimensions.

▸ Attachments:

Affected product list 1_cip20003_a
Qualification plan 2_cip20003_a

▸ Time Schedule:

■ Final qualification report:	available
■ First samples available:	request
■ Intended start of delivery:	21-March-2021

If you have any questions, please do not hesitate to contact your local Sales office.